

ABSTRACT

PROCESS FOR ADJUSTING THE RESISTANCE OF A CHIP RESISTOR

A process is provided for adjusting the resistance of a chip resistor which comprises an insulating chip substrate (1), a resistor film (3) formed on the chip substrate (1), and an undercoat layer (4) formed on the resistor film (3). The process comprising the steps of forming a trimming groove (10) in the resistor film (3) and the undercoat layer (4) by irradiating these with a laser beam while causing the chip substrate (1) and the laser beam to move intermittently relative to each other. The laser beam is collected so that the trimming groove (10) has a width of 15-45 μ m, whereas the chip substrate (1) and the laser beam are moved intermittently relative to each other at a pitch of 7-15 μ m.

(To be accompanied by Fig. 6)